

AMENDMENTS TO THE SPECIFICATION

Page 1

Please replace paragraph [0003] with the following amended paragraph:

[0003] In light devices that utilize a diode-based light source, the diode may include pins that are connected to electrical wiring for providing power to the diode. Other devices use surface-mounted diodes, in which each diode is affixed to a mounting plate that includes solder pads. Electrical power connections may be soldered onto these pads to provide the LED power. Examples of such surface-mounted LEDs include the LUXEON™ Star LED module ~~in~~ and the LUXEON Star/O LED module, which are currently available on the commercial market.

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Please replace paragraph [0037] with the following amended paragraph:

[0037] Figures 1 – 2B are ~~pre-vided~~ provided for purposes of illustration only. These figures are not intended to show, with any precision, the relative dimensions, sizes, and shapes of the various components. For example, the size of certain components may be exaggerated in relation to other components to more clearly illustrate them. It should also be noted that various modifications may be made to the configuration shown in these figures without departing from the spirit and scope of the invention, as will be contemplated by those of ordinary skill in the art.

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Please replace paragraph [0043] with the following amended paragraph:

[0043] According to an exemplary embodiment, the slots 232A and 232B may be located within a thermally insulating module at the mounting assembly 20. In the exemplary embodiments as shown in Figures 1 – 2B, the ~~therm-ally~~ thermally insulating module is comprised of two modular wear blocks 230A and 230B, each of which includes a corresponding one of the slots 232A and 232B. The wear blocks 230A and 230B may be formed of a thermally insulating material, such as plastic, which allows for an LT fit with the locating pins 120A and 120B.

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Please replace paragraph [0049] with the following amended paragraph:

[0049] As described above, the low-conductive plate 210 may be positioned on the mounting assembly 20, so as to cover the front of the mounting plate 220. Accordingly, when the quick attachment device is in the closed position, as illustrated in Figures 2 – 2B, the ~~low-co-nductive~~ low-conductive plate 210 is placed in abutment with the quick attachment module 10.

Please replace paragraph [0051] with the following amended paragraph:

[0051] As shown in Figures 1 – 2A, the ~~low-e-nductive~~ low-conductive plate 210 includes an aperture through which the diode 30 protrudes. According to an exemplary

Birch, Stewart, Kolasch & Birch, LLP

embodiment, this opening in the low-conductive plate 210 provides a close fit for the protruding diode 30. Furthermore, in the particular exemplary embodiment where the diode light source 30 is being tested by an integrating sphere 40, the front of the low-conductive plate 210 may be painted white, or otherwise given the same light reflective characteristics of the interior surfaces of the integrating sphere 40. Accordingly, the front surface of the low-conductive plate 210 may act as an extension of the interior surface of the integrating sphere 40 for any gaps between the opening in the integrating sphere 40 (located at testing position 150) and the diode light source 30, when testing is performed.

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Please replace paragraph [0060] with the following amended paragraph:

[0060] Figures 3A – 4C are ~~p-revided~~ provided in order to illustrate two particular exemplary embodiments. While the power supply device 210 is not limited to such embodiments, these Figures provide a general understanding of the components and principles related to a power supply device 210 for diode light source modules, whose power interface utilizes solder pads.

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Please replace paragraph [0063] with the following amended paragraph:

[0063] Figures 3A and 4A illustrate the front surface of the power supply device 210. Particularly, when this power supply device 210 is affixed to the mounting assembly 20 of the quick attachment device, the front surface illustrated in Figures 3A and 4A will be the surface

facing the quick attachment module 10. Figures 3B – 3C and ~~Figures~~ Figures 4B – 4C illustrate the reverse surface, i.e., the surface facing the mounting plate 220 on the mounting assembly 20.

Please replace paragraph [0065] with the following amended paragraph:

[0065] The placement of contact pads 213 on flexible tabs 214 allow for the power supply device 210 to compensate for a relative height differential with respect to the solder pads of a diode light source module. Figure 5 illustrates a profile view of a diode light source module utilizing a solder pad type power interface, according to an exemplary embodiment. In particular, Figure 5 illustrates a profile view of a diode light source module 500 (e.g., a surface-mounted LED), whose mounting plate 220 acts as a base. In particular, a power interface of the module 500 includes solder pads 513A and 513B. Because of, for example, a manufacturing defect or gradual wear, the height a of solder pad 513A is greater than the height b of solder pad 513B. The difference between heights ~~a and b (a-b)~~ a and b (a-b) may be referred to as a relative height differential between solder pads 513A and 513B.

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Please replace paragraph [0070] with the following amended paragraph:

[0070] Accordingly, when implemented in the mounting assembly 20 of the quick attachment device illustrated in Figures 1 – 2CB, these electrical pathways 215 will be insulated from both the mounting plate 220 and the quick disconnect hinges 110A and 110B of the quick attachment module 10.

Please replace paragraph [0071] with the following amended paragraph:

[0071] In the above exemplary embodiments, which are illustrated in Figures 3A – 4C, the power supply device is implemented as the low-conductive plate 210 of the mounting assembly 20 in the quick attachment device of Figures 1 – 2CB. However, it should be noted that this power supply device is not limited to such an application, and may be utilized apart from the quick attachment device. Furthermore, the power supply device described above is not limited to the testing of diode light sources.